

# P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	$R_{DS(on)}$ (Ω) $I_{D}$ (A) <sup>a</sup> Q			
- 60	0.019 at V <sub>GS</sub> = - 10 V	- 80	76 nC		
	0.025 at V <sub>GS</sub> = - 4.5 V	- 70	70110		

### FEATURES

- TrenchFET<sup>®</sup> Power MOSFET
- 100 % UIS Tested

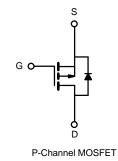
#### **APPLICATIONS**

Load Switch





## D<sup>2</sup>PAK (TO-263)



Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	- 60	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20		
	T <sub>C</sub> = 25 °C		- 80 <sup>a</sup>	
Continuous Drain Current (T = $150 ^{\circ}$ C)	T <sub>C</sub> = 70 °C		- 70	
Continuous Drain Current ( $T_J = 150 \ ^{\circ}C$ )	T <sub>A</sub> = 25 °C	- I <sub>D</sub> -	9.2 <sup>b</sup>	А
	T <sub>A</sub> = 70 °C		- 8.1 <sup>b</sup>	A
Pulsed Drain Current		I <sub>DM</sub>	- 150	1
Avalanche Current Pulse	L = 0.1 mH	I <sub>AS</sub>	- 45	
Single Pulse Avalanche Energy	L = 0.1 mm	E <sub>AS</sub>	101	mJ
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	I <sub>S</sub>	69 <sup>a</sup>	А
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	'S	2.1 <sup>b</sup>	A
	T <sub>C</sub> = 25 °C		104.2 <sup>a</sup>	
Movimum Dower Discipation	T <sub>C</sub> = 70 °C	P	66.7 <sup>a</sup>	w
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.1 <sup>b</sup>	vv
	T <sub>A</sub> = 70 °C		2 <sup>b</sup>	1
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b</sup>	Steady State	R <sub>thJA</sub>	33	40	°C/W	
Maximum Junction-to-Case	Steady State	R <sub>thJC</sub>	0.98	1.2	0/00	

Notes:

a. Based on  $T_C = 25 \ ^{\circ}C$ .

b. Surface mounted on 1" x 1" FR4 board.

Parameter	Symbol	Test Conditions	Min.	Turn	Max	Unit	
Static	Symbol	Test Conditions	wiin.	Тур.	Max.	Unit	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = - 250 μA	- 60	1	1	V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	VGS - 0 V, ID - 200 µA	- 00	68		v	
V <sub>GS(th)</sub> Temperature Coefficient		Ip = - 250 UA		- 5.2		mV/°C	
	$\Delta V_{GS(th)}/T_J$	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = - 250 μA	- 1	- 5.2	- 3	V	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>		- 1	-	-	•	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}$			- 1	0 μA	
		$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			- 10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	- 120			A	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A		0.019		Ω	
	D3(011)	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 20 A		0.025			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 50 A	20			S	
Dynamic <sup>b</sup>					-		
Input Capacitance	C <sub>iss</sub>			3500		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ = - 25 V, $V_{GS}$ = 0 V, f = 1 MHz		390			
Reverse Transfer Capacitance	C <sub>rss</sub>			290			
	Qg	$V_{DS} = -30$ V, $V_{GS} = -10$ V, $I_{D} = -55$ A		76		nC	
Total Gate Charge				38			
Gate-Source Charge		$V_{DS} = -30$ V, $V_{GS} = -4.5$ V, $I_{D} = -55$ A		16			
Gate-Drain Charge	Q <sub>gd</sub>			19			
Gate Resistance	Rg	f = 1 MHz		5.2		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			10	15		
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 2 V, $R_L$ = 2 $\Omega$		7	15	1	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong$ - 10 A, $V_{GEN}$ = - 10 V, $R_g$ = 1 $\Omega$		70	110	ns	
Fall Time	t <sub>f</sub>			40	60	-	
Drain-Source Body Diode Characteristics	5						
Continuous Source-Drain Diode Current	ا <sub>S</sub>	T <sub>C</sub> = 25 °C			- 69	T	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 150	A	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 30 A		- 1	- 1.5	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			45	68	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			59	120	nC	
Reverse Recovery Fall Time	ta	I <sub>F</sub> = - 50 A, di/dt = 100 A/μs, T <sub>J</sub> = 25 °C		29	-	ns	
Reverse Recovery Rise Time	t <sub>b</sub>			16			

Notes:

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

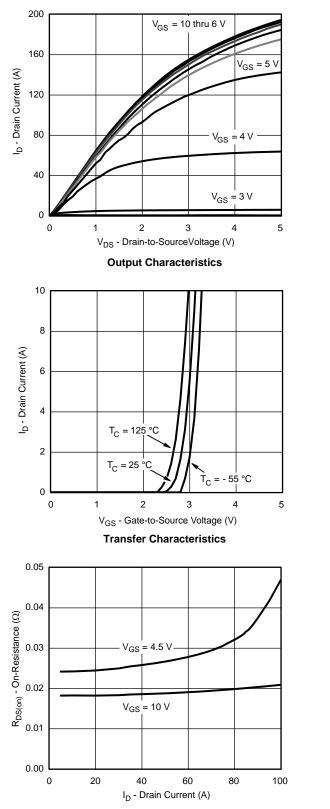
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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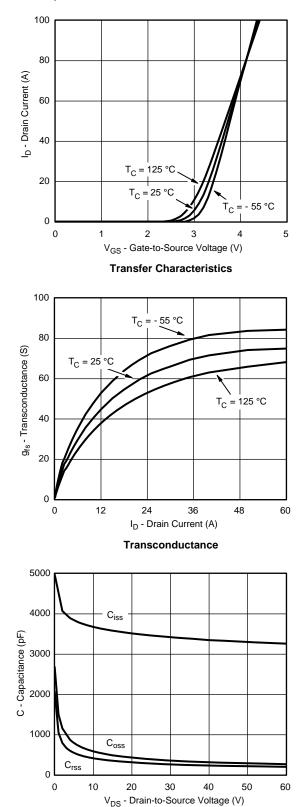
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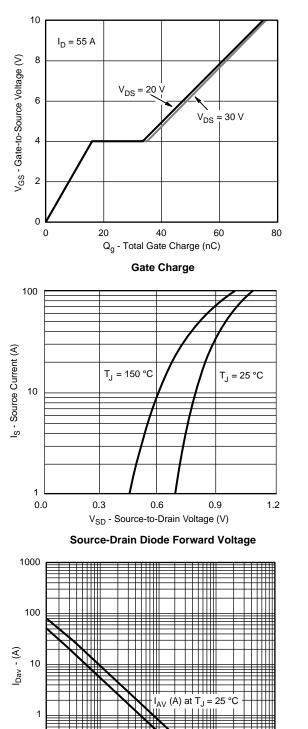
#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

**On-Resistance vs. Drain Current** 



Capacitance





### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

 $\label{eq:Tin-s} T_{\text{in}} \text{-} (s)$  Single Pulse Avalanche Current Capability vs. Time

0.01

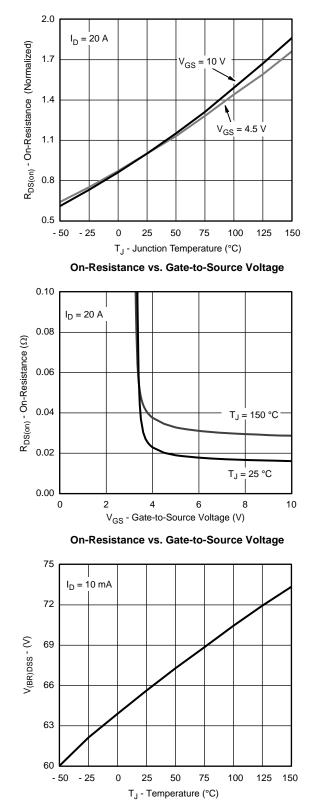
0.1

1

11111

 $I_{AV}$  (A) at  $T_{J}$  = 150

0.001

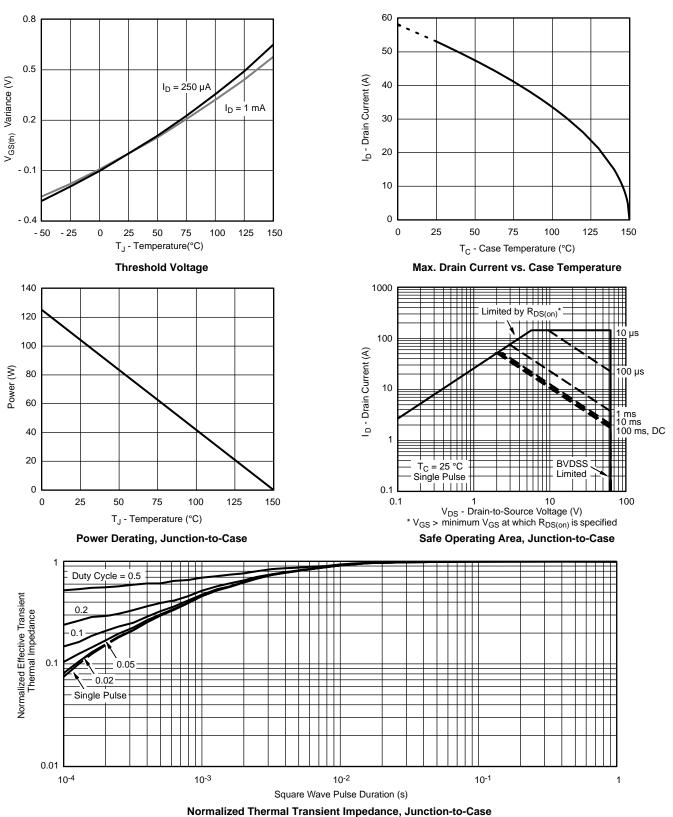


Drain-Source Breakdown Voltage vs. Junction Temperature

0.1

0.0001

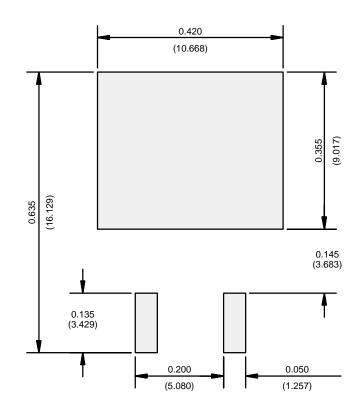




#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



### **RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)



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